

THIN FILM DEPOSITION LEYBOLD UNIVEX 900

 Villach

BRIEF DESCRIPTION

Thin-film deposition tool with manual loading of single wafers up to 200mm.

RESEARCH SERVICES

- E-beam evaporation system with 4 pockets
- DC and RF sputtering with 3 magnetron cathodes

METHODS & EXPERTISE ON THE RESEARCH INFRASTRUCTURE

The UNIVEX900 is an advanced coating system which can perform co-sputtering and e-beam evaporation in the same chamber in the same chamber. This tool is compatible with 8-inch wafers (200 mm) and can be used to deposit many materials such as metals, oxides or nitrides.

Magnetron sputtering:

- Three magnetron sources, housing 100mm targets (indirectly or Directly cooled targets)
- Two source generators: DC (1500 W) and RF (600 W)
- Co-sputtering, reactive sputtering (O₂ / N₂)
- Bias generator, holder's heating / cooling

E-beam evaporation:

- 4-pocket turret from Ferrotec (EV M-6, 8cc)
- E-beam acceleration voltage: 10 kV
- E-beam gun power: 5 kW
- Crucible-to-Wafer distance: > 90 cm
- PID-controlled deposition rate

CONTACT

Heimo Müller

✉ heimo.mueller@silicon-austria.com

🌐 <https://silicon-austria-labs.com/>

